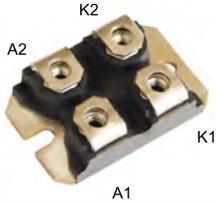
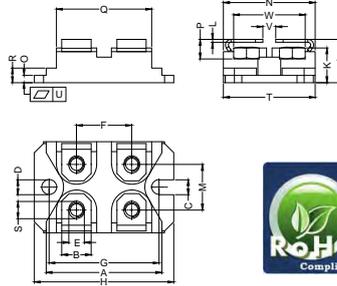


MBR2X120-200

<][\ 'H'a ' @k ' FFA 'GW ch_m6 Uff]Yf '8]cXYg'



Dimensions SOT -227(ISOTOP)



Dim.	Millimeter		Dim.	Millimeter	
	Min.	Max.		Min.	Max.
A	31.30	31.65	M	12.00	13.00
B	7.80	8.40	N	25.15	25.65
C	4.00	4.30	O	1.95	2.15
D	Ø4.00	Ø4.30	P	5.60	6.60
E	4.00	4.30	Q	25.30	26.30
F	14.90	15.20	R	3.90	4.30
G	30.10	30.30	S	4.45	4.85
H	38.00	38.50	T	24.50	25.10
J	12.10	12.90	U	0.05	0.10
K	9.00	9.60	V	3.00	4.80
L	0.75	0.85	W	19.30	20.50



	VRSM V	VRRM V
MBR2X120-100	100	100
MBR2X120-150	150	150
MBR2X120-200	200	200

Symbol	Test Conditions	Maximum Ratings	Unit
IFRMS		180	
IFAVM	T _C =110°C; rectangular, d=0.5; per chip	120	A
IFAVM	T _C =110°C; rectangular, d=0.5; per device	240	
IFSM	T _{VJ} =45°C; t _p =10ms (50Hz), sine	1500	A
EAS	I _{AS} =28A; L=180uH; T _{VJ} =25°C; non-repetitive	128	mJ
IAR	V _A =1.5·V _{RRM} typ.; f=10kHz; repetitive	3.2	A
(dv/dt) _{cr}		1000	V/us
T _{VJ}		-40...+150	°C
T _{VJM}		150	
T _{stg}		-40...+150	
P _{tot}	T _C =25°C	330	W
V _{ISOL}	50/60Hz, RMS; I _{ISOL} ≤1mA	2500	V~
M _d	mounting torque (M4); terminal connection torque (M4)	1.1-1.5/9-13	Nm/lb.in.
Weight	typical	30	g

Symbol	Test Conditions	Characteristic Values			Unit
		typ.	max.		
I _R	T _{VJ} =25°C; V _R =V _{RRM} T _{VJ} =125°C; V _R =V _{RRM}		4 12		mA
V _F	I _F =120A; T _{VJ} =125°C I _F =120A; T _{VJ} =25°C I _F =240A; T _{VJ} =125°C	100V 0.75	150V 0.77	200V 0.85	
R _{thJC} R _{thCH}		0.11		0.38	K/W

FEATURES

- * International standard package SOT-227
- * Isolation voltage 2500 V~
- * 2 independent Schottky diodes in 1 package
- * Very low V_F
- * Extremely low switching losses
- * Low IRM-values
- * RoHS compliant

APPLICATIONS

- * Rectifiers in switch mode power supplies (SMPS)
- * Free wheeling diode in low voltage converters

ADVANTAGES

- * High reliability circuit operation
- * Low voltage peaks for reduced protection circuits
- * Low noise switching
- * Low losses

Sirectifier®

MBR2X120-200

<][\ 'H'a ' @k 'FFA 'GW ch_m6 Uff]Yf '8]cXYg'

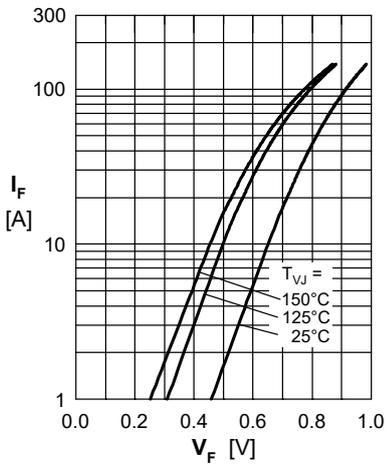


Fig. 1 Maximum forward voltage drop characteristics

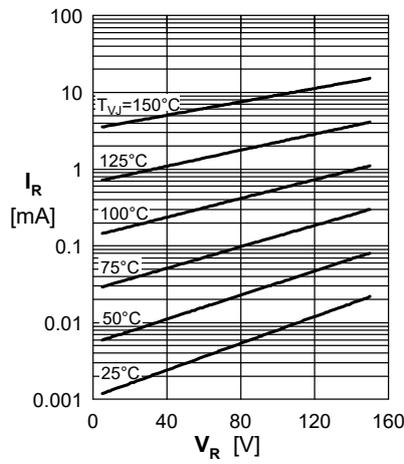


Fig. 2 Typ. reverse IR vs. reverse voltage VR current

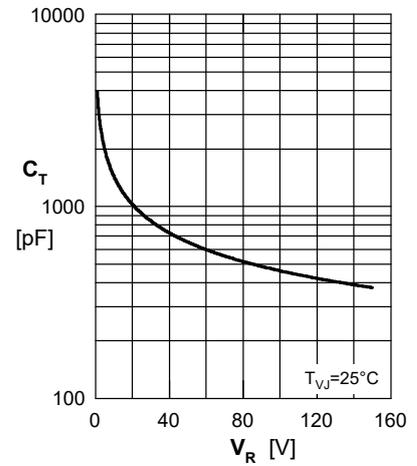


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

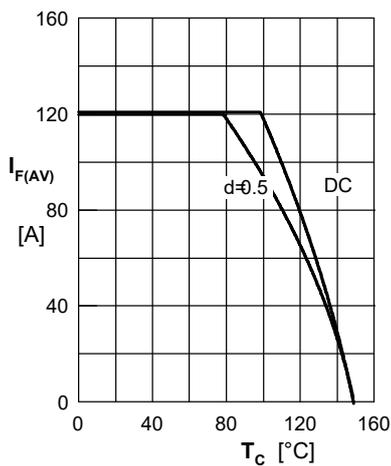


Fig. 4 Average forward current $I_{F(AV)}$ vs. case temperature T_C

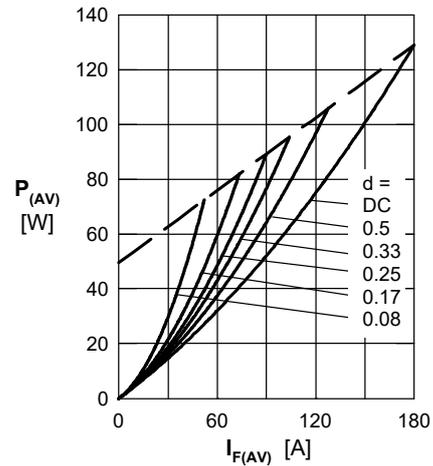


Fig. 5 Forward power characteristics loss

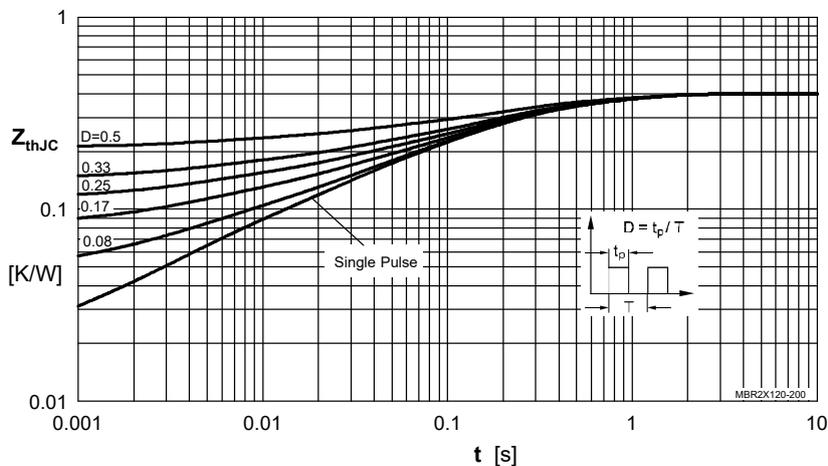


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode

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